

Final Product/Process Change Notification

Document #: FPCN22071X Issue Date: 20 November 2017

Title of Change:	Transfer of Final Test location of former Fairchild Small Signal Transistor in SOIC-16 leads package to ON Semiconductor Carmona, Philippines.	
Proposed first ship date:	27 February 2018	
Contact information:	Contact your local ON Semiconductor Sales Office or <zbd6nn@onsemi.com></zbd6nn@onsemi.com>	
Samples:	Contact your local ON Semiconductor Sales Office	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <ffw3zw@onsemi.com></ffw3zw@onsemi.com>	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>	
Change Part Identification:	Customer may receive the parts test in ON Semiconductor Carmona, Philippines from month of Feb 2018 once FPCN expire or earlier depending on customers' approvals. Parts tested in ON Semiconductor Philippines can be identified through product packaging and labelling which follow ON Semiconductor standard.	
Change category:	☐ Wafer Fab Change ☐ Assembly Change	☐ Other
Change Sub-Category(s): □ Datasheet/Product Doc change ☑ Manufacturing Site Change/Addition □ Material Change ☑ Shipping/Packaging/Marking ☑ Manufacturing Process Change ☐ Other:		⊠ Shipping/Packaging/Marking
Sites Affected:	ON Semiconductor Sites: ON Carmona, Philippines	External Foundry/Subcon Sites: Amkor, Philippines

Description and Purpose:

This Final Notification announces to customers of its plan to transfer Test operation site of former Fairchild Small Signal Transistor in SOIC-16 package from existing external manufacturing facility to internal manufacturing site ON Semiconductor Carmona, Philippines.

The Philippines internal facility is certified with ISO/TS 16949:2009 and is currently running production for SOC-16 package.

These products will continue being Pb-free, Halide free and RoHS compliant. Qualification tests are designed to show that the reliability of the transferred devices will continue to meet or exceed ON Semiconductor standards.

Material to be changed	Before Change Description	After Change Description
Pizza Box	338x334x43mm (5ku/box)	330x336x49mm (2.5k u/box)
Reel and Pizza Box Labelling	LOT: BASINITYN FSD: FAN'ISMA D.CI: SHANC QUTI: Graz Compand: GUTY: 1560 G	(1F) MPN : NCP1608BDR2G (17) LOT: 0128271UDK (18) LOT: 0128271UDK (18) LOT: 0128271UDK (17) LOT: 0128271UDK (18) LOT: 0128271UDK (18) LOT: 0128271UDK (18) LOT: 0128271UDK (19) LOT: 0128271UDK (19) LOT: 0128271UDK (19) LOT: 0128271UDK (17) LOT: 0128271UD

TEM001793 Rev. O Page 1 of 2



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Reliability Data Summary:			
No change in form, fit and functions of the devices. Reliability Testing is not required.			
Electrical Characteristic Summary:			
Data are available upon request.			
List of Affected Standard Parts:			
Part Number	Qualification Vehicle		
MMPQ2907A			
MMPQ2222A			
MMPQ3904	MMPQ6700		
MMPQ3906			
MMPQ6700			

TEM001793 Rev. O Page 2 of 2